

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A holder for semiconductor as well as liquid-crystal manufacturing devices, the holder comprising:

a ceramic susceptor of an aluminum nitride ceramic of porosity of 0.03% or less whose thermal conductivity is 100 W/mK or more, said susceptor having a retaining side for retaining an object to be processed, said retaining side having a warpage of 500 μm or less and a surface roughness of under 5 μm Ra;

a resistive heating element incorporated in said susceptor, said resistive heating element patterned in a circuit having a thickness of 5 to 100 μm and a pattern spacing of 0.1 mm or more; and

a metal plate having a thermal conductivity higher than that of said ceramic susceptor, said metal plate mechanically attached to said susceptor opposite said retaining side by an adhesive bonding layer, by screws screwed into said susceptor, or by a recess provided in said metal plate, into which said susceptor is snug-fit, whereby the higher thermal conductivity of said metal plate than, together with said metal plate's mechanical attachment to, said susceptor promote diffusion of heat from said resistive heating element toward said retaining side,

whereby the temperature uniformity of the holder in operation is within $\pm 0.5\%$.

Claim 2 (canceled)

Claim 3 (original): A holder as set forth in claim 1, wherein the resistive heating element is present beyond the middle in the thickness direction of said susceptor, toward the side opposite said retaining side.

Claim 4 (canceled)

Claim 5 (canceled)

Claim 6 (canceled)

Claim 7 (canceled)

Claim 8 (previously presented): A holder as set forth in claim 1, wherein said metal is any one selected from Al-SiC, Cu-W and Cu-Mo.

Claim 9 (original): A holder as set forth in claim 1, wherein the thickness of said metal plate is thicker than the thickness of said ceramic susceptor.

Claim 10 (original): A holder as set forth in claim 1, wherein the diameter of said ceramic susceptor is 200 mm or more.

Claim 11 (canceled)

Claim 12 (canceled)

Claim 13 (original): A semiconductor manufacturing device in which the holder of claim 1 is installed.

Claim 14 (original): A liquid-crystal manufacturing device in which the holder of claim 1 is installed.

Claim 15 (currently amended): A holder for semiconductor as well as liquid-crystal manufacturing devices, the holder comprising:

a ceramic susceptor of an aluminum nitride ceramic of porosity of 0.03% or less and whose thermal conductivity is 100 W/mK or more, said susceptor having a

retaining side for retaining an object to be processed, said retaining side having a warpage of 500 μm or less and a surface roughness of under 5 μm Ra;

a resistive heating element incorporated in said susceptor, said resistive heating element patterned in a circuit having a thickness of 5 to 100 μm and a pattern spacing of 0.1 mm or more; and

a metal plate made of one selected from Al-SiC, Cu-W and Cu-Mo to have a thermal conductivity greater than that of said susceptor, said metal plate fastened to said susceptor opposite said retaining side by an adhesive bonding layer, by screws screwed into said susceptor, or by a recess provided in said metal plate, into which said susceptor is snug-fit, whereby the higher thermal conductivity of said metal plate than, together with said metal plate's mechanical attachment to, said susceptor promote diffusion of heat from said resistive heating element toward said retaining side,

whereby the temperature uniformity of the holder in operation is within $\pm 0.5\%$.

Claim 16 (currently amended): A holder for semiconductor as well as liquid-crystal manufacturing devices, the holder comprising:

a ceramic susceptor 200 mm or more in diameter, of an aluminum nitride ceramic of porosity of 0.03% or less and whose thermal conductivity is 100 W/mK or more, said susceptor having a retaining side for retaining an object to be processed, said retaining side having a warpage of 500 μm or less and a surface roughness of under 5 μm Ra;

a resistive heating element incorporated in said susceptor and therein present beyond the middle in the thickness direction of said susceptor, toward the side

opposite said retaining side, said resistive heating element patterned in a circuit having a thickness of 5 to 100 μm and a pattern spacing of 0.1 mm or more; and

a metal plate made of one selected from Al-SiC, Cu-W and Cu-Mo to have a thermal conductivity greater than that of said susceptor, said metal plate fastened to said susceptor opposite said retaining side by an adhesive bonding layer, by screws screwed into said susceptor, or by a recess provided in said metal plate, into which said susceptor is snug-fit, whereby the higher thermal conductivity of said metal plate than, together with said metal plate's mechanical attachment to, said susceptor promote diffusion of heat from said resistive heating element toward said retaining side,

whereby the temperature uniformity of the holder in operation is within $\pm 0.5\%$.